

1-10. (CANCELED)

11. (CURRENTLY AMENDED) The thermal conductive material according to claim ~~[[10]]~~ 19, wherein the thermal conductive material is plasticized at 60°C under a pressure equal to or above 6.0 g/cm². ◆◆

12. (CURRENTLY AMENDED) The thermal conductive material according to claim ~~[[10]]~~ 19, wherein the unvulcanized organic material has a melting transition in the range of 30-70°C and a viscosity at 100°C is equal to or above 70,000cP, a weight ratio of the filler to the thermal conductive material is in the range of 30-90%. ◆◆

13. (CURRENTLY AMENDED) The thermal conductive material according to claim ~~[[10]]~~ 19, wherein the thermal conductive material is in an elastomeric state at room temperature. ◆◆

14. (CURRENTLY AMENDED) The thermal conductive material according to claim ~~[[10]]~~ 19, wherein the organic material is an olefin resin. ◆◆

15. (CANCELED)

16. (CURRENTLY AMENDED) The thermal conductive material according to claim ~~[[10]]~~ 19, wherein the filler is at least one of ceramics, metallic powder, metallic magnetic body and carbon fiber. ◆◆

17. (CURRENTLY AMENDED) The thermal conductive material according to claim ~~[[10]]~~ 19, wherein the filler is a material serving as an electromagnetic shield. ◆◆

18. (CANCELED)

19. (CURRENTLY AMENDED) A thermal conductive material comprising:
 an unvulcanized EPDM material ~~having a weight average molecular weight of between 7,000-50,000~~; and ◆◆
 a filler having a higher thermal conductivity than the unvulcanized EPDM material, ◆◆

 wherein the thermal conductive material is plasticized at a temperature in the range of 30-65°C and the thermal conductive material changes form to flexibly correspond to a form of a surface of a member with which the thermal conductive material comes in contact.